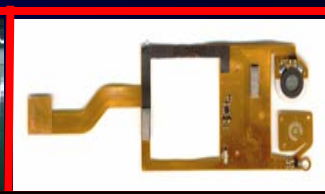
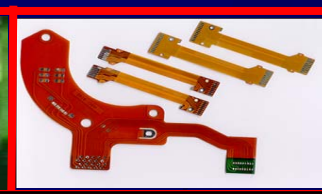
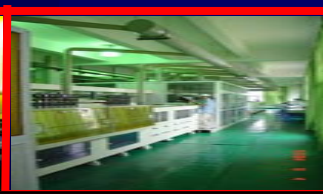
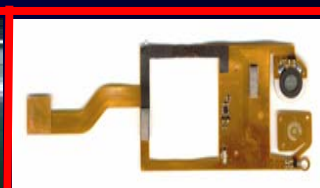
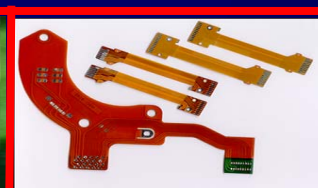
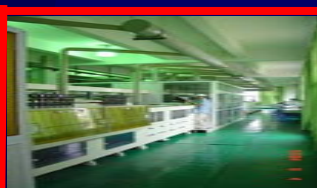


- GuangZhou Factory established in April 1994
- Single & Double Sided FPC production started in 1996
- UL certified in December 1996
- “Creative Hi-Tech. Enterprise” award given by GuangZhou Government in 2001

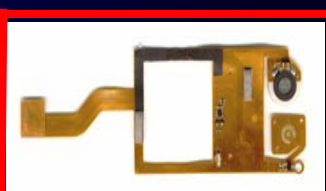
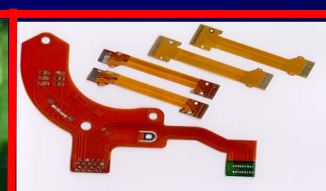


- “R & D Center” established in 2001
- Multi-layer FPC production started in 2001
- Flex-Rigid Production started in November 2004
- Suzhou Factory established in Suzhou in March 2005
- Shenzhen Factory established in Shenzhen in July 2005
- Fine Pitch (0.075/0.075mm) FPC production started in August 2005



Guangzhou Factory

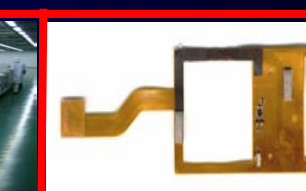
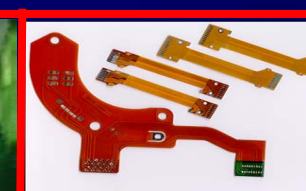
- Capital Investment: USD 21,700,000
- Total Investment: USD 35,000,000
- Floor Space: 25,000 M²
- Employees: 880



- Production Capacity:
40,000 M² / Month
- Capability: 5 Full Lines
 - Single Side FPC
 - Double Side FPC
 - Multi-Layer FPC
 - Fine Pitch FPC
 - Rigid-Flex PCB

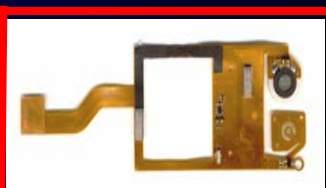
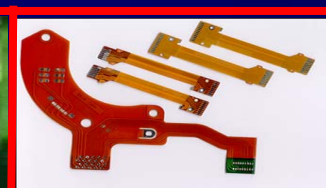
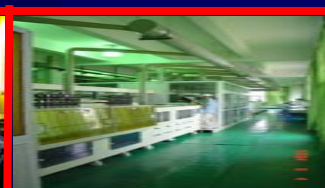


DES Production Line



Shenzhen Factory

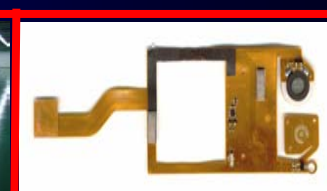
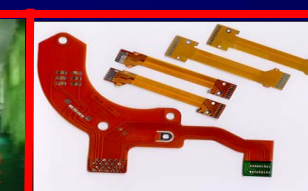
- Capital Investment:
HKD 30,000,000
- Business:
SMT on FPC
- Floor Space:
3,000 M²
- Employees: 260



- Capacity: 8 SMT lines
 - 5 Juki Lines
 - 3 Fuji high speed Lines
 - 6 millions dots / day
- Capability:
 - BGA
 - 0201 Components
 - 0.4mm pitch IC
 - Lead free

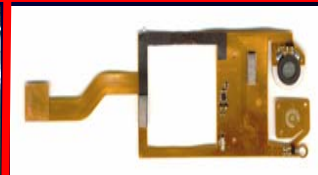
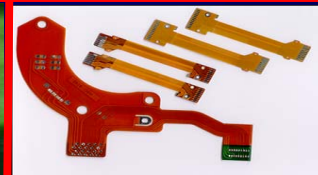


SMT Assembly Line



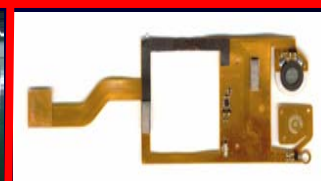
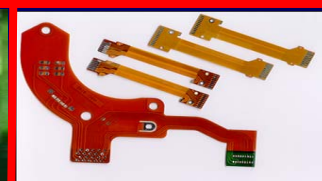
FPC Capability

- Materials Used
 - Polyimide, Polyester
- Maximum Panel Size
 - 19.7" x 24" (500 x 610 mm)
- Line width & Spacing
 - 3 mil (0.075 mm)
- Copper thickness
 - 1/3 oz Min.
- Layer to Layer Registration
 - ± 5 mil (0.13 mm)
- Minimum Drill hole Dia.
 - 4 mil (0.1 mm)
- Minimum Via Size
 - 4 mil (0.1 mm)
- Lands / Pads
 - 16 mil (0.4 mm)
- Plasma etching for through holes

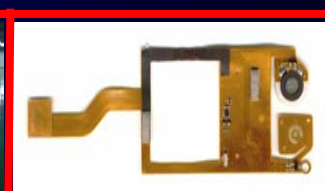
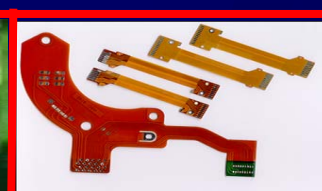


■ Surface Finish

- Hard Gold / Immersion Gold (ENIG)
- Lead free HAL
- Tin Lead Plating
- Tin Plating
- Lead based HAL

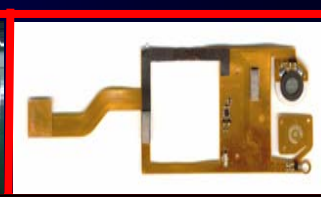
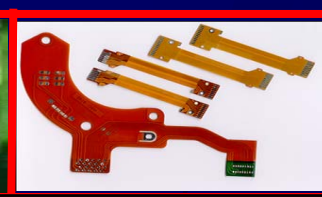
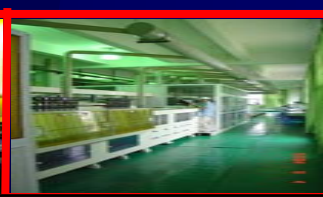


- Cover layer
 - Polyimide
 - Flexible Solder Mask
- Stiffener material
 - Polyimide
 - Polyester
 - FR4
 - Metal
- Shielding material
 - Copper foil
 - Silver foil
 - Silver Paste
- Assembly on FPC (Through-hole and SMT)
 - 0201 component
 - 0.4 mm pitch IC & connector



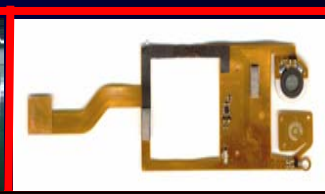
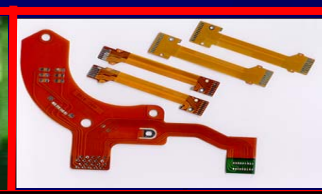
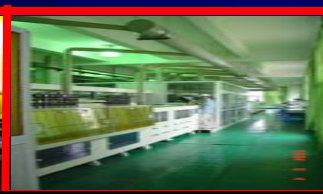
Capital Equipment

Measurement	Qty
• Copper Thickness Measurement	2
• A-A Analysis Instrument	1
• Peel Strength Tester	2
• Micro-Section Analysis Instrument	1
• OPTEK 2D Measurement	3
• Ionic contamination Tester	1
• X-Ray Thickness Measuring	
Cu / Ni / Au / thickness	1
• Microscope for Through Holes	2



Functional Testing Equipment Qty

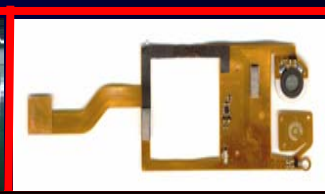
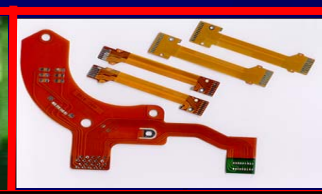
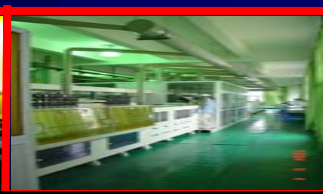
- Flying Probe Open/Short Tester 2
- Open / Short Tester 12
- AOI 1
- TDR Characteristic Impedance 1
- Insulation Instrument 1
- High Voltage Tester 1



Reliability Testing Equipment

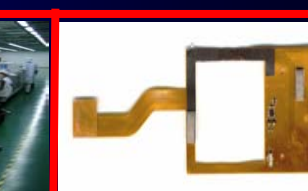
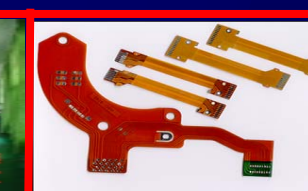
Qty

- Flexibility Tester 1
- Bending Tester 1
- Folding Tester 1
- Mobile Phone Life time Tester 3
- Humidity & Temperature Chamber 2
- Salt Fog Testing Chamber 1

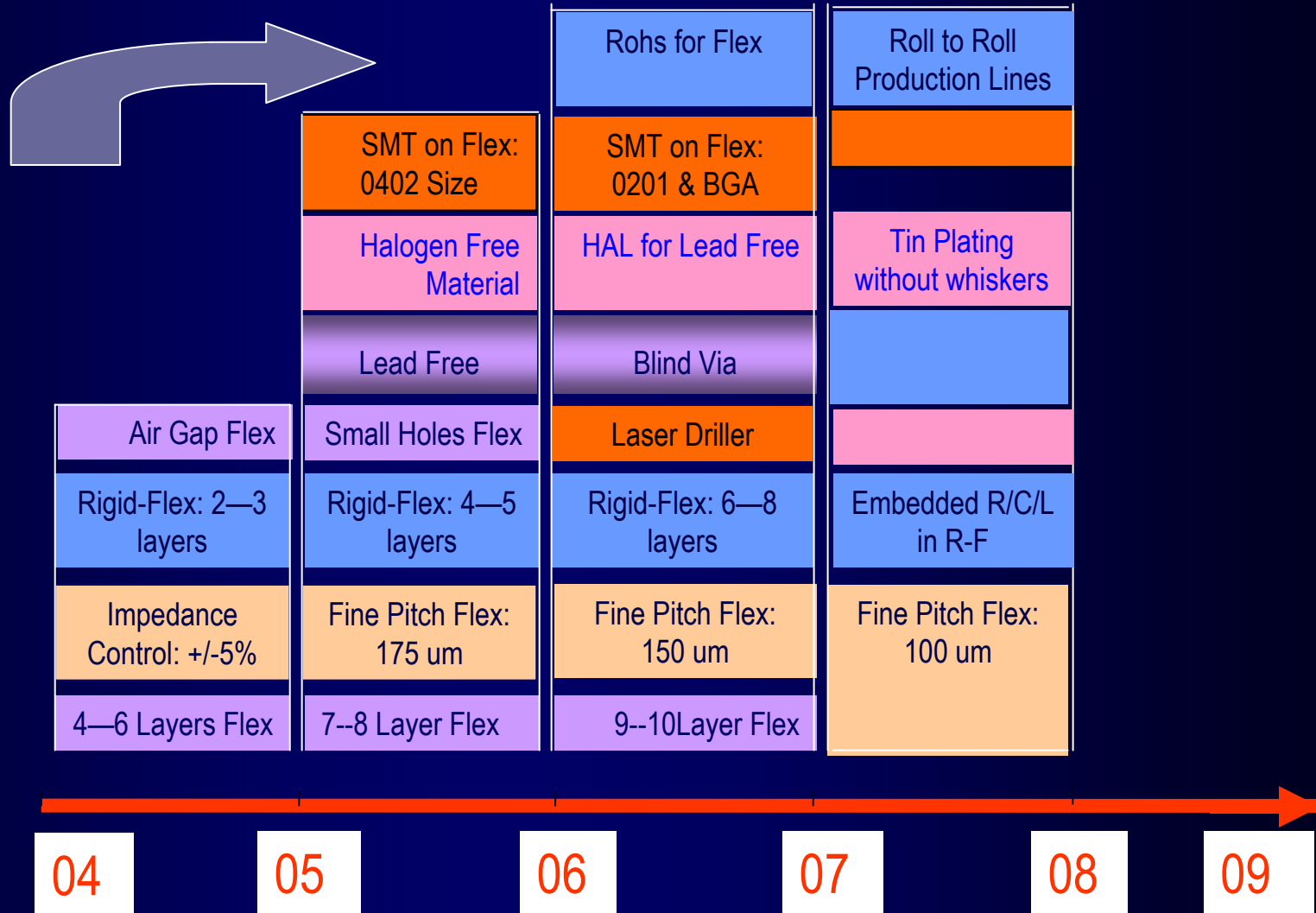


Lead time

		Special Order	Normal Time
Prototype	Single Sided	1 weeks	2 weeks
	Double Sided	1 weeks	2 weeks
	Multi-layer	1 weeks	2 weeks
Mass Production	Single Sided	2 weeks	3 weeks
	Double Sided	2 weeks	3 weeks
	Multi-layer	2 weeks	4 weeks

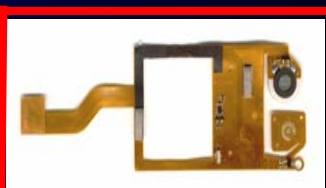
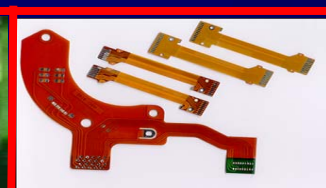
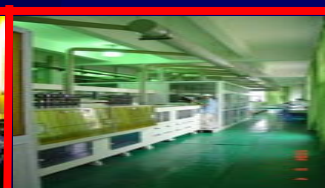


Road map of Technologies



Milestones of Quality Assurance

- UL Certification (Dec. 1995)
- ISO9002:1994 (July. 1996)
- ISO9001:2000 (Jan.2003)
- QS9000:1998 (Dec. 2004)
- ISO14001:2004 (May. 2005)
- TS16949:2002 (Dec. 2006)
- LG Green Partner (Dec. 2006)



Quality Control

•IQC

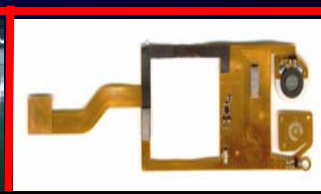
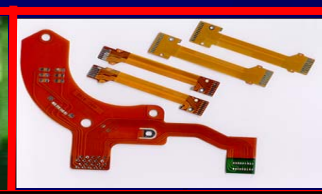
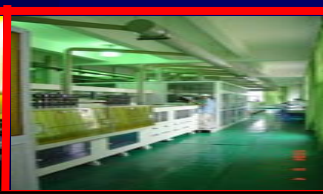
- Copper Thickness
- CCL Thickness
- Flex base material Thickness
- Peel Strength
- Solder flow test
- Chemical Checking

•PQC/PQA

- Micro-section for Copper thickness (after plating)
- Open / Short
- Dimension
- Impedance Control
- Chemical Checking

•FQC/FQA

- 100 % ET for O/S
- 100% Visual Inspection
- Impedance
- Peel Strength
- Flexibility
- ICT



Quality Assurance System

Sales Dept.

Customer Service Engineer

- Customer Document Review
- Customer Quality Service

Manufacturing Dept.

Quality Control

- Product Quality Lot Assurance
- Micro section for hole quality checking
- Semi-Product Visual Inspection
- Semi-Product O/S & AOI Test
- Final 100% O/S Test
- Final 100% Visual Inspection

Q . A

Process Quality Engineer

- New Article Evaluation
- Document & Tooling Verification
- Incoming Quality Control
- In-Process Quality Audit (Operation/Parameter)
- Semi-Product Micro-section
- SPC System
- Calibration System
- Quality Training

Quality Assurance

- Out-Going Quality Sampling Plan
- Packing & Shipping Monitor
- Reliability Test
- CAR System
- Quality System Audit
- Failure Analysis



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